

**In the Specification:**

Please amend the second full paragraph on page 5 as follows:

In another embodiment consistent with the present invention, the Backside Interconnect includes plated-through ground vias disposed on the MMIC, which tie to ~~terminal pins~~ terminals on the substrate.

Please amend the second full paragraph on page 9 as follows:

For example, plated-through ground vias 104 for the Backside Interconnect are disposed in the GaAs MMIC 102, and tie to two ~~terminal pins~~ terminals 108 on the RF header 101, and rest vias (not shown) tie to the bottom ground plane of the RF header 101.

Please amend the first paragraph on page 11 as follows:

In one embodiment consistent with the present invention, a low dielectric conformal coating 106 with a dielectric constant suitable for operating at an operational frequency between 2 and 10 GHz, will seal the microchips from inorganic and organic liquid and vapors, for additional protection.